

Semiconductor Packaging Market by Type (Flip-Chip, Embedded Die, Fan-In WLP, and Fan-Out WLP), Packaging Material (Organic Substrate, Bonding Wire, Leadframe, Ceramic Package, Die Attach Material, and Others), Wafer Material (Simple Semiconductor (Silicon (Si) and Germanium (Ge)) and Compound Semiconductor (III-V (Gallium Arsenide (GaAs), Indium Phosphide (InP), Gallium Nitride (GaN), Gallium Phosphide (GaP), and Others), II-VI (Zinc Sulfide (ZnS) and Zinc Selenide (ZnSe)), and IV-IV (Silicon Carbide (SiC) and Silicon-Germanium (SiGe)), and Technology (Grid Array, Small Outline Package, Flat No-Leads Packages (Dual-flat no-leads (DFN) and Quad-flat no-leads (QFN)), Dual In-Line Package (Plastic Dual Inline Package (PDIP) and Ceramic Dual Inline Package (CDIP)), and Others), and Industry Vertical (Consumer Electronics, Automotive, Healthcare, IT & Telecommunication, Aerospace & Defense, and Others): Global Opportunity Analysis and Industry Forecast, 2021–2030

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Abstracts

The global semiconductor packaging market is expected to reach \$60.44 billion by 2030 from \$27.10 billion in 2020, growing at a CAGR of 9.10% from 2021 to 2030.

Semiconductor packaging refers to the material that contains a semiconductor device. This package is a case that surrounds the circuit material to protect it from corrosion or physical damage and allow mounting of the electrical contacts connecting it to the printed circuit board (PCB). With rapid growth in the semiconductor packaging market, specifically fan out wafer level packaging along with increasing demand for smartphone and devices and Internet of Things (IoT), packaging suppliers are developing processes and ways to reduce the overall cost of advanced packaging and provide maximum operational efficiency. During recent times, packaging is mainly used for high-end products and for applications related to niche-market, such as wafer and die production, due to its high cost in its operation.

The prominent factors that drive the growth of the semiconductor packaging market include growth of Internet of Things (IoT) technology, high adoption of consumer electronics devices, and evolving trends toward semiconductor wafers in the automotive industry. However, high cost associated with semiconductor packaging materials hampers its adoption, which is expected to pose a major threat to the global semiconductor packaging market. However, evolving trends toward the fan-out wafer level packaging are expected to provide lucrative opportunities to the market growth.

The global semiconductor packaging is segmented into type, packaging material, wafer material, technology, industry vertical, and region. Based on type, the market is divided into flip-chip, embedded die, fan-in WLP, and fan-out WLP. On the basis of packaging material, it is analyzed across organic substrate, bonding wire, leadframe, ceramic package, die attach material, and others. On the basis of wafer material, it is fragmented into simple semiconductor and compound semiconductor. Simple semiconductor is further sub-segmented into silicon (Si) and germanium (Ge). Compound semiconductor is further sub-segmented into III-V (Gallium Arsenide (GaAs), Indium Phosphide (InP), Gallium Nitride (GaN), Gallium Phosphide (GaP), and others), II-VI (Zinc Sulfide (ZnS) and Zinc Selenide (ZnSe)), and IV-IV (Silicon Carbide (SiC) and Silicon-Germanium (SiGe)). Based on technology, the market is categorized into grid array, small outline package, flat no-leads packages (Dual-flat no-leads (DFN) & Quad-flat no-leads (QFN)), dual in-line package (Plastic Dual Inline Package (PDIP) & Ceramic Dual Inline Package (CDIP)), and others.

By industry vertical, the market is studied across consumer electronics, automotive, healthcare, IT & telecommunication, aerospace & defense, and others. The automotive

segment accounted for the highest market share in 2020, whereas the consumer electronics segment is expected to grow at the highest CAGR from 2021 to 2030. By region, the semiconductor packaging market trends are analyzed across the North America, Europe, Asia-Pacific, and LAMEA.

KEY MARKET SEGMENTS

BY TYPE

Flip Chip

Embedded DIE

Fan-in WLP

Fan-out WLP

BY PACKAGING MATERIAL

Organic Substrate

Bonding Wire

Leadframe

Ceramic Package

Die Attach Material

Others

BY WAFER MATERIAL

Simple Semiconductor

Silicon (Si)

Germanium (Ge)

Compound Semiconductor

III-V

Gallium Arsenide (GaAs)

Indium Phosphide (InP)

Gallium Nitride (GaN)

Gallium phosphide (GaP)

Others

II-VI

Zinc Sulfide (ZnS)

Zinc Selenide (ZnSe)

IV-IV

Silicon Carbide (SiC)

Silicon-Germanium (SiGe)

BY TECHNOLOGY

Grid Array

Small Outline Package

Flat no-leads packages

Dual-flat no-leads (DFN)

Quad-flat no-leads (QFN)

Dual In-Line Package

Plastic Dual Inline Package (PDIP)

Ceramic Dual Inline Package (CDIP)

Others

BY END USER

Consumer Electronics

Automotive

Healthcare

IT & Telecommunication

Aerospace & Defense

Others

BY REGION

North America

U.S.

Canada

Mexico

Europe

UK

Germany

France

Italy

Rest of Europe

Asia-Pacific

China

Japan

India

South Korea

Taiwan

Rest of Asia-Pacific

LAMEA

Latin America

Middle East & Africa

KEY PLAYERS

Amkor Technology, Inc.

ASE Group

ChipMOS Technologies, Inc.

Powertech Technology, Inc.

Fujitsu Ltd.

Intel Corporation

Texas Instruments

Jiangsu Changjiang Electronics Technology Co., LTD

Samsung Electronics Co., Ltd.

Taiwan Semiconductor Manufacturing Company

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